



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : ST25R3916/17/18/16B/17B, NFC Reader IC new product introduction
with non-wettable thin QFN package

PCI Reference : MDG/22/13712

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

ST25R3916-AQWT	ST25R3917B-AQWT	ST25R3916B-AQWT
ST25R3918-AQWT	ST25R3917-AQWT	



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ST25R3916/17/18/16B/17B, NFC Reader IC new product introduction with non-wettable thin QFN package

What is the change?

The ST25R3916/17/18/16B/17B-AQWT currently assembled at UTAC (Thailand) in wettable flank QFN package will be assembled & tested in non-wettable flank thin QFN at JSCC (China) with a new product ordering code ST25R3916/17/18/16B/17B-AQET.

The ST25R3916/17/18/16B/17B-AQET are fully compatible with current AQWT versions with same functionalities and electrical features.

Package size of the new non-wettable flank thin QFN package is compatible with current QFN package. Package thickness of the new non wettable flank thin QFN is reduced from 1mm to 0.6mm. Refer to the datasheet for a list of all dimensions.

Concurrent to this change, the ams OSRAM wafer fab 8 (Austria) will be implemented as a second source for the new products ST25R3916/17/18/16B/17B-AQET in addition to the TSMC wafer fab 10 (China), wafer fab process flow and equipment do not change.

Customers will be informed in time before this second source will be activated.

Current ST25R3916/17/18/16B/17B-AQWT will only be available for low volumes, not recommended for new designs, ST recommends the new ST25R3916/17/18/16B/17B-AQET for faster availability and to secure demand.

Why?

ST is committed to ensure delivery to its customers and needs to react to market situations trying to mitigate any potential delivery bottlenecks in advance to ensure best delivery times and availability to customers.

When?

First products can be shipped by wk44 2022. Flow used and final good delivered is at the discretion of ST.

How will the change be qualified?

The new product has been qualified using the standard STMicroelectronics Corporate and MMY (Memory) division Procedures for Quality and Reliability.

The Qualification Report RERMMY2202 will be available on request after Week 45/2022.

What is the impact of the change?

- **Form:** Marking change (see details next page)
- **Fit:** Package dimensions: Package thickness change and dimension of solder pin.
- **Function:** No change

How can the change be seen?

- **BOX LABEL MARKING**

On the BOX LABEL, the difference is visible on the Commercial Part Number and the Finished Good part Number. Also, the change is visible inside the Trace code where the “Assembly Country & Plant” digits are reflecting the new plant as **GQ** for **JSCC (China)** instead of FN for UTAC (Thailand):

→ Example for ST25R3916-AQET

STMicroelectronics

Manufactured under patents or patents pending

Country Of Origin: XXXX

Pb-free 2nd Level Interconnect

MSL: 3

PBT: 260 °C

TYPE: ST25R3916-AQET


25R3916-AQETRASB

Total Qty: **3000**

Trace Codes GQYWWLLL P2 GQ

Marking 25R3916

Bulk ID X0X00XXX0000



Please provide the bulk ID for any inquiry

Commercial Part Number:

E: new products in non-wettable flank thin QFN (JSCC (China) assembly)

W: current products in wettable flank QFN (UTAC (Thailand) assembly)

Finished Good Part Number:

A: new products manufactured at ams OSRAM wafer fab second source

T: current & new products manufactured at TSMC wafer fab

GQ: JSCC (China) assembly country & plant

FN: current UTAC (Thailand) assembly country & plant

GQ: JSCC (China) Test & Finishing country & plant

FN: current UTAC (Thailand) Test & Finishing country & plant

P2: ams OSRAM wafer fab 8 (Austria)

S9: current TSMC wafer fab 10 (Taiwan)

ST25R3916/17/18/16B/17B, NFC Reader IC new product introduction
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How can the change be identified?

- **Form: DEVICE MARKING**

On the device marking, the change is visible inside the trace code where the Assembly Country & Plant “PP” is changing from FN to **GQ**. Also, the Country Of origin “HHH” is changing from THA to **CHN**.



Legend:

25R3916 = Product name

PP = Assembly Country & plant: - **GQ** for **new product assembled & tested at JSCC (China)**
- FN for current product at UTAC (Korea)

LLL = Sequence

WX = wafer plant : **P2** for product manufactured in ams OSRAM wafer fab (Austria)
 S9 for product manufactured in TSMC fab 10 (Taiwan)

HHH = Country of origin: - **CHN** for **new product**, THA for current product.

Y = Assembly year

WW = Assembly week

Appendix A- Product Change Information

Product family / Commercial products:	NFC Reader IC
Customer(s):	All
Type of change:	New product introduction
Reason for the change:	Service improvement
Description of the change:	New product introduction
Forecast date of the change: (Notification to customer)	Week 41 / 2022
Forecast date of <u>Qualification samples</u> availability for customer(s):	See details in APPENDIX B
Forecast date for the internal STMicroelectronics change, <u>Qualification Report</u> availability:	Pending
Marking to identify the changed product:	ST25R391x-AQET on Box Label
Description of the qualification program:	Standard ST Microelectronics Corporate Procedures for Quality and Reliability
Product Line(s) and/or Part Number(s):	See Appendix B
Manufacturing location:	ams OSRAM AG, Austria TSMC Shanghai, China JSCC, China
Estimated date of first shipment:	Samples : Available Production : wk44

ST25R3916/17/18/16B/17B, NFC Reader IC new product introduction
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Appendix B: Concerned Commercial Part Numbers:

Current Commercial Part Numbers	New Commercial Part Numbers	Samples availability
ST25R3916-AQWT	ST25R3916-AQET	Available
ST25R3917-AQWT	ST25R3917-AQET	Nov/2022
ST25R3918-AQWT	ST25R3918-AQET	Apr/2023
ST25R3916B-AQWT	ST25R3916B-AQET	Jan/2023
ST25R3917B-AQWT	ST25R3917B-AQET	Jan/2023

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Document Revision History		
Date	Rev.	Description of the Revision
Sept. 12, 2022	V01	First draft.

Source Documents & Reference Documents		
Source document Title	Rev.:	Date: